10/22/2014 503028546

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT3075146

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chih-Wei Yang	09/04/2014
Yu-Feng Liu	09/04/2014
Jian-Cun Ke	09/04/2014
Chia-Fu Hsu	10/20/2014
Yu-Ru Yang	10/20/2014
En-Chiuan Liou	10/20/2014

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14520342

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2336USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	10/22/2014

Total Attachments: 12 source=2085020#page1.tif source=2085020#page2.tif

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Title of Invention:

INTEGRATED CIRCUIT AND METHOD OF FORMING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	filed	filed on		
☐ PCT international application	n number	fi	led on	**************************************
The above-identified application was	made or authorize	ed to be made by me	·	
I believe that I am the original invent application.	or or an original joi	nt i nv entor of a clain	ned invention in th	е
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement m isonment of not mo	ade in this declarati ore than five (5) year	on is punishable s, or both.	
In consideration of the payment by	UNITED MICRO	DELECTRONICS	having a posta	ıl address of
No.3, Li-Hsin Road 2, Science	-Based Industr	ial Park, Hsin-Ch	u City 300, Tai	wan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of Or ad valuable conside	ne Dollar (\$ 1.00), theration.	e receipt of which	is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all im tion and, in and to, rany continuations	provements which a all Letters Patent to , continuation-in-part	re disclosed in the be obtained for sa t, divisions, renewa	e aid als.
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement n this assignment;	or encumbrance ha	s been or will be n	nade or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	ition and said Lette stify as to the same	rs Patent and legal e in any interference	equivalents as ma , litigation proceed	v be
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said inven cessary or desirab	tion and said Letters le to carry out the pr	Patent and said oposes thereof.	Pate of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivale s form. Use this for	ent), including namin m for <u>each additiona</u>	g the entire Il inventor.	

Page 1 of 12

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372

ME OF INVENTOR(ASSIGNOR)		- 1
Chih-Wei Yang	Date	9/4,2014
Chih-Wei	Tang	
	Chih-Wei Yang	· · · · · · · · · · · · · · · · · · ·

Page 2 of 12

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372 F#NPO-P0002E-US1201 DSC0-103U007841

Title of Invention: INTEGRATED CIRCUIT AND METHOD OF FORMING THE SAME

As the below named inventor, I here This declaration is directed to:	eby declare that:		
☑ The attached application, or	•		
☐ United States application nu	imber	filed on	, or
☐ PCT international application	n number	filed on	•
The above-identified application was	s made or authorized to be made	by me.	
I believe that I am the original inventapplication.	or or an original joint inventor of a	a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	l false statement made in this de isonment of not more than five (5	claration is punishable) years, or both.	
In consideration of the payment by	UNITED MICROELECTROICORP.	NICS having a postal add	iress of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hs	in-Chu City 300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1.0 and valuable consideration.	00), the receipt of which is he	reby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, an I hereby covenant that no assignmen	nd to any and all improvements w tion and, in and to, all Letters Pat any continuations, continuation- ad as to Letters Patent any reissu	which are disclosed in the sent to be obtained for said in-part, divisions, renewals, e or re-examination thereof.	
entered into which would conflict with	this assignment;	ice has been of will be made	or
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters Patent and l stifv as to the same in any interfe	legal equivalents as may be	ts
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said L cessary or desirable to carry out	etters Patent and said the proposes thereof.	f signing)
Note: An application data sheet (PTC nventive entity, must accompany this	o/SB/14 or equivalent), including r s form. Use this form for <u>each ado</u>	naming the entire litional inventor.	

Page 3 of 12

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372

LEGAL NA	ME OF INVENTOR(ASSIG	inor)		
Inventor:	Yu-Feng Liu		Date:	9/4.2014
Signature:	2u - F	eng	Sin	· · ·
		0		

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F#NPO-P0002E-US1201 DSC0-103U007841

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372

Title of Invention:

INTEGRATED CIRCUIT AND METHOD OF FORMING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:				
☑ The attached application, or					
☐ United States application number			filed on , o		or
☐ PCT international application	number		filed on		
The above-identified application was	made or authorized	to be made by	me.		
I believe that I am the original inventorapplication.	or or an original joint	inventor of a c	laimed inv	ention in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement mad sonment of not more	de in this decla than five (5) y	ration is pure ears, or bo	unishable oth.	
In consideration of the payment by	UNITED MICROE Corp.	ELECTRONIC	CS hav	ing a postal addre	ess of
No.3, Li-Hsin Road 2, Science	-Based Industria	l Park, Hsin-	 -Chu City	/ 300, Taiwan,	R.O.C.
(referred to as "ASSIGNEE" below) to acknowledged, and for other good and I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, and I hereby covenant that no assignment entered into which would conflict with I further covenant that ASSIGNEE will	d valuable consideral SSIGNEE and the s d to any and all imprion and, in and to, al any continuations, c d as to Letters Pater t, sale, agreement or this assignment; I, upon its request, b	uccessors and rovements which I Letters Paten ontinuation-in-put any reissue or encumbrance	assignees ch are disc t to be obte part, division re-exami has been	of the ASSIGNE losed in the ained for said ons, renewals, ination thereof. or will be made o	E
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. N WINTNESS WHEREOF, I have hereunto set hand and seal this SEP 0 4 2014 (Date of signing)					
Note: An application data sheet (PTO inventive entity, must accompany this	/SB/14 or equivalent form. Use this form	t), including nar for <u>each additi</u> d	ming the ei onal invent	ntire cor.	

Page 5 of 12

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Jian-Cun Ke

Date: >c14/c9/c4

Signature: Tran - Com KR

Page 6 of 12

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372 F#NPO-P0002E-US1201 DSC0-103U007841

Title of Invention: INTEGRATED CIRCUIT AND METHOD OF FORMING THE SAME

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☐ United States application nu	mber	filed o	n	, (or
☐ PCT international application	n number		d on		
The above-identified application was	s made or authorized to be made	by me.			
I believe that I am the original inventapplication.	or or an original joint inventor of a	claimed	d invention in	the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this dec isonment of not more than five (5)	claration) years,	is punishabl or both.	e	
In consideration of the payment by	UNITED MICROELECTRON CORP.	lics	having a po	stal addre	ss of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	n-Chu	City 300, ⊺	Taiwan, I	R.O.C.
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I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, an	nd to any and all improvements witten and, in and to, all Letters Pater any continuations, continuation-ind as to Letters Patent any reissue	hich are ent to be n-part, d e or re-e:	disclosed in obtained for ivisions, rene xamination ti	the said ewals, hereof.	
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbrand or this assignment;	ce has b	een or will b	e made or	•
further covenant that ASSIGNEE with and documents relating to said invention and accessible to I and will tear the thereto and will promptly executed the same and will be same a	tion and said Letters Patent and lo stify as to the same in any interfer	egal equ	ivalents as r	nav he	
representatives any and all papers, ir maintain, issue and enforce said app equivalents thereof which may be ne N WINTNESS WHEREOF, I have he	lication, said invention and said Le cessary or desirable to carry out tl	etters Pa he propo	atent and sai	d (Date of s	igning)
Note: An application data sheet (PTC nventive entity, must accompany this	n/SB/14 or equivalent), including n form. Use this form for <u>each add</u>	aming th	ne entire ventor.		

Page 7 of 12

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Chia-Fu Hsu

Date:

OCT 20 2014

Signature: Chra-fru Hsu

Page 8 of 12

F#NPO-P0002E-US1201 DSC0-103U007841

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372

Title of Invention: INTEGRATED CIRCUIT AND METHOD OF FORMING THE SAME

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☐ United States application number			iled on , or	
☐ PCT international application	n number		filed on	
The above-identified application was	made or authorized	to be made by n	ne.	
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(referred to as "ASSIGNEE" below) to acknowledged, and for other good an I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an I hereby covenant that no assignmen entered into which would conflict with	SSIGNEE and the side of the si	lion. Iccessors and asovements which Letters Patent to the continuation in patent in the continuation in	ssignees of the As are disclosed in the obe obtained for s rt, divisions, renev re-examination the	SSIGNEE he said wals, ereof.
I further covenant that ASSIGNEE wil and documents relating to said invent known and accessible to I and will tes related thereto and will promptly exec	tion and said Letters Stify as to the same in	Patent and legal	equivalents as ma	av ha
representatives any and all papers, in maintain, issue and enforce said appl equivalents thereof which may be ned N WINTNESS WHEREOF, I have he	ication, said inventior essarv or desirable t	n and said Letter o carry out the p	s Patent and said roposes thereof.	Date of signing)
Note: An application data sheet (PTO nventive entity, must accompany this	/SB/14 or equivalent) form. Use this form f	, including nami or <u>each addition</u>	ng the entire al inventor.	

Page 9 of 12

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Yu-Ru Yang	Date:	OCT 20	2014		
Signature:	y-Ryg	····				

Page 10 of 12

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372

Title of Invention: INTEGRATED CIRCUIT AND METHOD OF FORMING THE SAME

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☐ United States application nu	mber	filed on	, or			
☐ PCT international application number		filed on	*			
The above-identified application was made or authorized to be made by me.						
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.						
I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.						
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(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration.						
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified application or substitutes, or extensions thereof, and hereby covenant that no assignment optered into which would are fit to the	nd to any and all improvements whiten and, in and to, all Letters Pate any continuations, continuation-indicate to Letters Patent any reissue to sale, agreement or encumbrance.	nich are disclosed in the ent to be obtained for said n-part, divisions, renewals e or re-examination thereo	, f.			
entered into which would conflict with	this assignment;	The state of the bound	ic 01			
I further covenant that ASSIGNEE wi and documents relating to said invent known and accessible to I and will tes related thereto and will promptly exec	tion and said Letters Patent and le stify as to the same in any interfer	egal equivalents as may be	_			
representatives any and all papers, ir maintain, issue and enforce said appl equivalents thereof which may be neo N WINTNESS WHEREOF, I have he	ication, said invention and said Lecessary or desirable to carry out the	etters Patent and said ne proposes thereof.	of signing)			
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire nventive entity, must accompany this form. Use this form for <u>each additional inventor.</u>						

Page 11 of 12

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372

Inventor: En-Chiuan Liou Date: OCT 20 2014

Page 12 of 12

F#NPO-P0002E-US1201 DSC0-103U007841

NPO#NAU-P2336-USA:0 CUST#UMCD-2014-0372

RECORDED: 10/22/2014